L Number	Hits	Search Text	DB	Time stamp
3	5	09/360292	USPAT; US-PGPUB	2004/10/21 09:34
31	13859	(trench groove hole via opening recess damascene) with (etch$3 with (gas plasma))	USPAT; US-PGPUB	2004/10/21 09:53
32	9410	((trench groove hole via opening recess damascene) with (etch$3 with (gas plasma))) and ((trench groove hole via opening recess damascene) with (insulat$4 dielectric))	USPAT; US-PGPUB	2004/10/21 09:53
33	1062	(((trench groove hole via opening recess damascene) with (etch$3 with (gas plasma))) and ((trench groove hole via opening recess damascene) with (insulat$4 dielectric))) and (trench groove hole via opening recess damascene) with ((chlorine 'cl' hydrogen 'h') with (gas plasma))	USPAT; US-PGPUB	2004/10/21 10:00
34	200	((((trench groove hole via opening recess damascene) with (etch$3 with (gas plasma))) and ((trench groove hole via opening recess damascene) with (insulat$4 dielectric))) and (trench groove hole via opening recess damascene) with ((chlorine 'cl' hydrogen 'h') with (gas plasma))) and (trench groove hole via opening recess damascene) with (silicide refractory)	USPAT; US-PGPUB	2004/10/21 09:58
35	75	(((((trench groove hole via opening recess damascene) with (etch$3 with (gas plasma))) and ((trench groove hole via opening recess damascene) with (insulat$4 dielectric))) and (trench groove hole via opening recess damascene) with ((chlorine 'cl' hydrogen 'h') with (gas plasma))) and (trench groove hole via opening recess damascene) with (silicide refractory)) and (trench groove hole via opening recess damascene) with ((chlorine 'cl') with (gas plasma))	USPAT; US-PGPUB	2004/10/21 10:43
36	5	09/360292	USPAT; US-PGPUB	2004/10/21 10:43
-	5	09/360292	USPAT; US-PGPUB	2004/03/03 08:18
-	184313	(trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)	USPAT; US-PGPUB	2004/10/21 09:52
-	8052	((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) and ((trench groove hole via opening recess damascene) with ((etch$3 clean$3 remov$4) near4 plasma))	USPAT; US-PGPUB	2004/03/03 08:27
-	2415	(((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) and ((trench groove hole via opening recess damascene) with ((etch$3 clean$3 remov$4) near4 plasma))) and (gas near4 plasma)	USPAT; US-PGPUB	2004/03/03 08:28
-	556	((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) and ((trench groove hole via opening recess damascene) with ((etch$3 clean$3 remov$4) near4 plasma))) and (gas near4 plasma)) and (plasma with hydrogen)	USPAT; US-PGPUB	2004/03/03 08:29
-	561	((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) and ((trench groove hole via opening recess damascene) with ((etch$3 clean$3 remov$4) near4 plasma))) and (gas near4 plasma)) and (plasma with (hydrogen 'h2'))	USPAT; US-PGPUB	2004/03/03 08:30
-	135	(((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) and ((trench groove hole via opening recess damascene) with ((etch$3 clean$3 remov$4) near4 plasma))) and (gas near4 plasma)) and (plasma with hydrogen)) and (plasma with (chlorine 'cl'))	USPAT; US-PGPUB	2004/03/03 08:30
-	137	(((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) and ((trench groove hole via opening recess damascene) with ((etch$3 clean$3 remov$4) near4 plasma))) and (gas near4 plasma)) and (plasma with (hydrogen 'h2'))) and (plasma with (chlorine 'cl'))	USPAT; US-PGPUB	2004/03/03 08:30
-	137	((((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) and ((trench groove hole via opening recess damascene) with ((etch$3 clean$3 remov$4) near4 plasma))) and (gas near4 plasma)) and (plasma with (hydrogen 'h2'))) and (plasma with (chlorine 'cl'))) and (trench groove hole via opening recess damascene etch$3 insulat$ dielectric etching hydrogen chlorine plasma substrate silicon)	USPAT; US-PGPUB	2004/03/03 08:31

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| - | 19 | ((((((((trench groove hole via opening recess damascene) with (etch\$3 insulat\$ dielectric)) and ((trench groove hole via opening recess damascene) with ((etch\$3 clean\$3 remov\$4) near4 plasma))) and (gas near4 plasma)) and (plasma with (hydrogen 'h2')) and (plasma with (chlorine 'cl'))) and (trench groove hole via opening recess damascene etch\$3 insulat\$ dielectric etching hydrogen chlorine plasma substrate silicon)) and ((trench groove hole via opening recess damascene) with (silicide refractory)) | USPAT; US-PGPUB | 2004/10/21 09:34 |
| - | 1 | 10/039517 | USPAT; US-PGPUB | 2004/03/03 09:14 |

Drafts
Pending
Active
L45: (16452) (trench groove hole via opening recess damascene) with ((etch$3 pattern$4) with (ga...
L46: (10122) 45 and ((trench groove hole via opening recess damascene) with (insulat$4 dielectric))
L47: (2318) 46 and ((hydrogen 'h') with (gas plasma))
L48: (458) 47 and ((chlorine) with (gas plasma))
L49: (320) 48 and ((substrate) with (gas plasma))
L50: (60) 49 and ((trench groove hole via opening recess damascene) with (silicide refactory))
Failed
(0) 46 and ((hydrogen 'h') with ((etch$3 pattern$4) with (gas plasma))
(0) 46 and (((hydrogen 'h') with ((etch$3 pattern$4) with (gas plasma))
Saved
(5) 09/360292
(184313) (trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)
(8052) ((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) an...
(2415) (((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) a...
(556) ((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) a...
(561) ((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric)) a...
(135) (((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric))...
(137) (((((trench groove hole via opening recess damascene) with (etch$3 insulat$ dielectric))...

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10/039517

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